

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Chad A. Cobbley et al.

Serial No.:

10/770,941

Filed:

February 03, 2004

For:

STACKED DIE MODULE AND

TECHNIQUES FOR FORMING A

STACKED DIE MODULE

Group Art Unit:

2813

Examiner:

Blum, David S.

88888888

Atty Docket: MICS:0078—2 (FLE)

(01-0752.02)

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313

CERTIFICATE OF TRANSMISSION OR MAILING 37 C.F.R. 1.8

I hereby certify that this correspondence is being transmitted by facsimile to the United States Patent and Trademark Office in accordance with 37 C.F.R. 1.6(d) or is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313, on the date below:

May 23, 2005

Date

Sir:

RESPONSE AND AMENDMENT

In response to the Final Official Action mailed on March 22, 2005, Applicants respectfully request reconsideration of the above-identified application in view of the amendments and remarks set forth below.